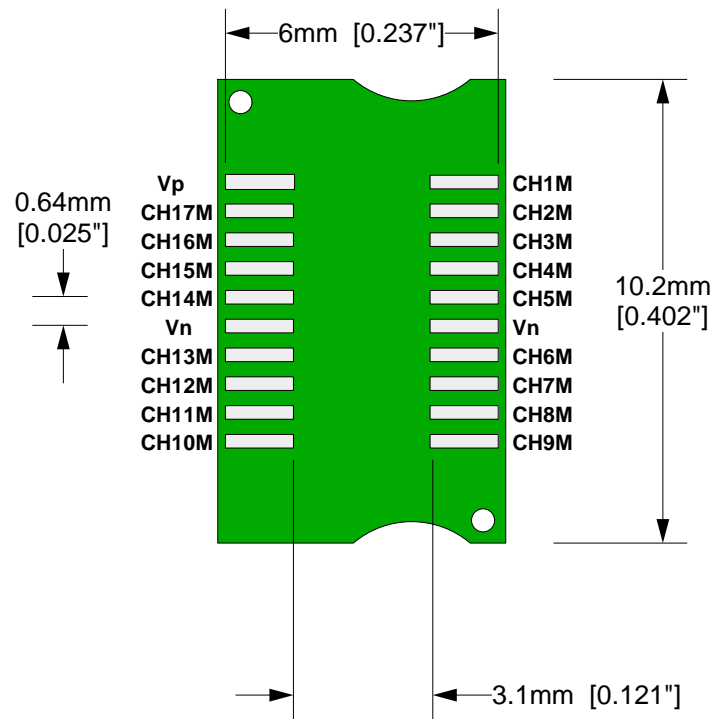
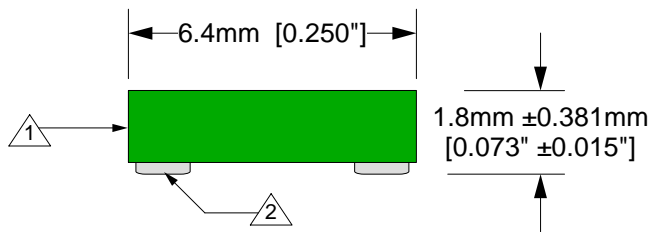


Top View

Side View



Bottom View




End View

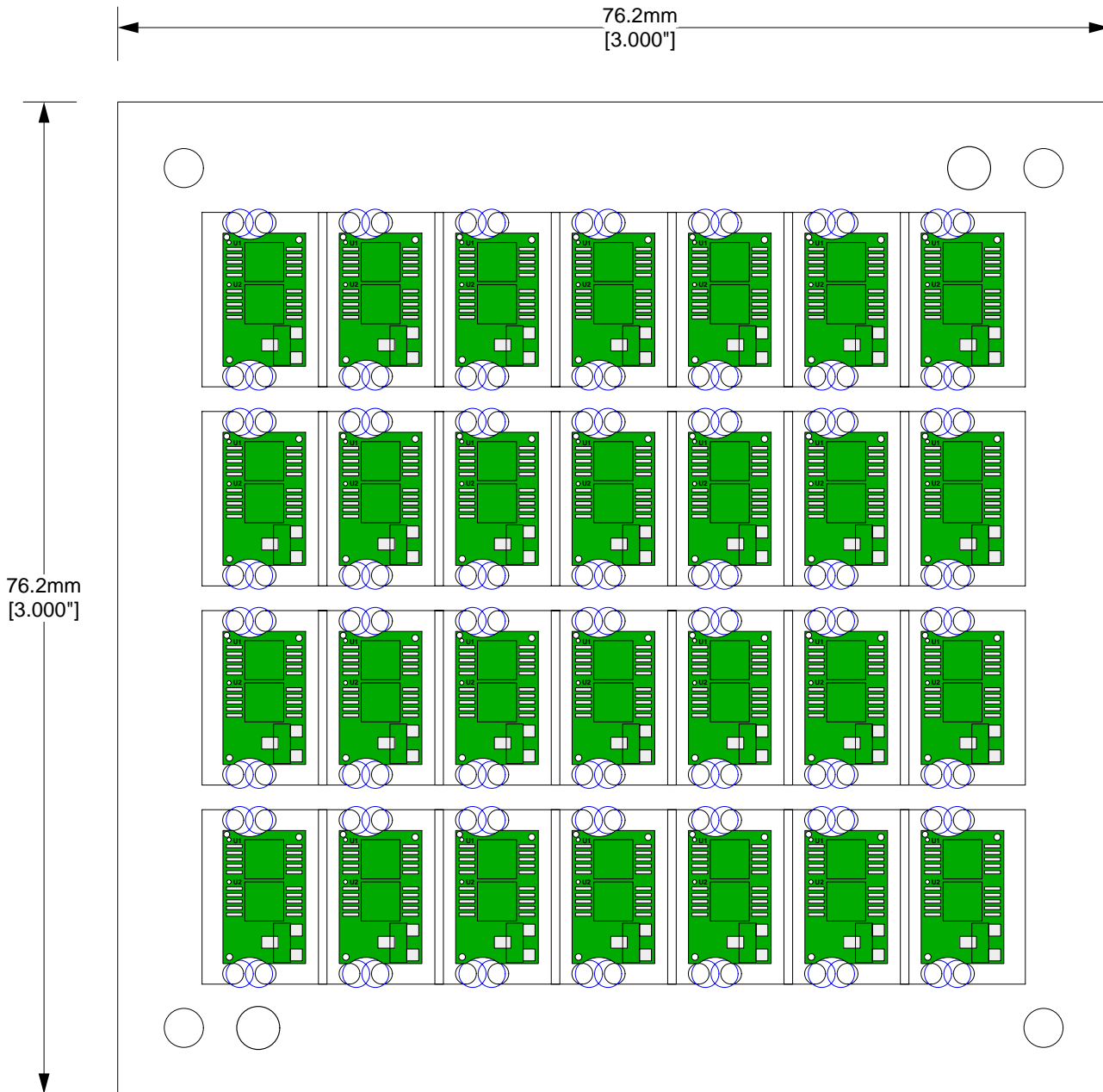
- △1 Substrate: 1.59mm ±0.18mm [0.0625" ±0.007"] FR4/G10 or equivalent high temp material. 17µm [1/2 oz.] Cu clad. SnPb plating.
- △2 Solder columns: Eutectic 63% Sn 37% Pb

Description: Package Converter


10 position (x2) 0.5mm SOIC land pads to 20 position 0.635mm pitch SOIC solder columns. Pin mapping is custom specific.

Tolerances: diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

| | | | | |
|---|--------------------------------|------------------|----------------|--------|
| DC-SO/SO-CM1213-F-01 Drawing | | Status: Released | Scale: 6:1 | Rev: A |
|  <p>© 2007 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p> | Drawing: J. Glab | | Date: 07/19/07 | |
| | File: DC-SO_SO-CM1213-F-01 Dwg | | Modified: | |



Tolerances: diameters $\pm 0.03\text{mm}$ [± 0.001 "], PCB perimeters $\pm 0.13\text{mm}$ [± 0.005 "], PCB thicknesses $\pm 0.18\text{mm}$ [± 0.007 "], pitches (from true position) $\pm 0.08\text{mm}$ [± 0.003 "], all other tolerances $\pm 0.13\text{mm}$ [± 0.005 "] unless stated otherwise. Materials and specifications are subject to change without notice.

| | | | |
|--|---------------------------------------|-----------------------|---------------|
| <p>DC-SO/SO-CM1213-F-01 Drawing</p> | <p>Status: Released</p> | <p>Scale: 6:1</p> | <p>Rev: A</p> |
|  <p>© 2007 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p> | <p>Drawing: J. Glab</p> | <p>Date: 07/19/07</p> | |
| | <p>File: DC-SO_SO-CM1213-F-01 Dwg</p> | <p>Modified:</p> | |